Switching Diodes

<u>Panasonic</u>

MA6X126 (MA126)

Silicon epitaxial planar type

For switching circuit

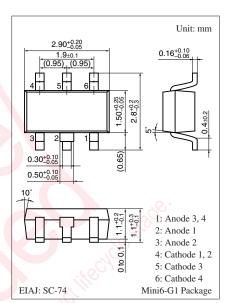
Features

- Four isolated elements contained in one package, allowing highdensity mounting
- High breakdown voltage: $V_R = 80 V$

Note) *1: Value for single diode *2: t = 1 s

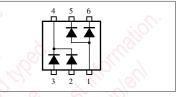
Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit		
Reverse voltage	V _R	80	V		
Maximum peak reverse voltage	V _{RM}	80	V		
Forward current *1	I _F	100	mA		
Peak forward current *1	I _{FM}	225	mA		
Non-repetitive peak forward surge current *1, 2	I _{FSM}	500	mA		
Junction temperature	Tj	150	°C		
Storage temperature	T _{stg}	-55 to +150	°C		



Marking Symbol: M2S

Internal Connection



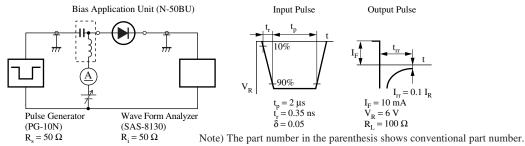
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_F = 100 \text{ mA}$	J.		1.2	V
Reverse voltage	VR	$I_R = 100 \ \mu A$	80	SOL		V
Reverse current	IR	V _R = 75 V	and a second		100	nA
Terminal capacitance	C _{t1} *1	$V_R = 0 V, f = 1 MHz$	2.2		15	pF
	C _{t2} *2				2	
Reverse recovery time *3	t _{rr1} *1	$I_F = 10 \text{ mA}, V_R = 6 \text{ V}$			10	ns
	t _{rr2} *2	$I_{rr} = 0.1 I_R$, $R_L = 100 \Omega$			3	

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

- 2. Absolute frequency of input and output is 100 MHz.
- 3. *1: Between pins 1 and 5, Between pins 1 and 6
 - *2: Between pins 4 and 2, Between pins 4 and 3

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

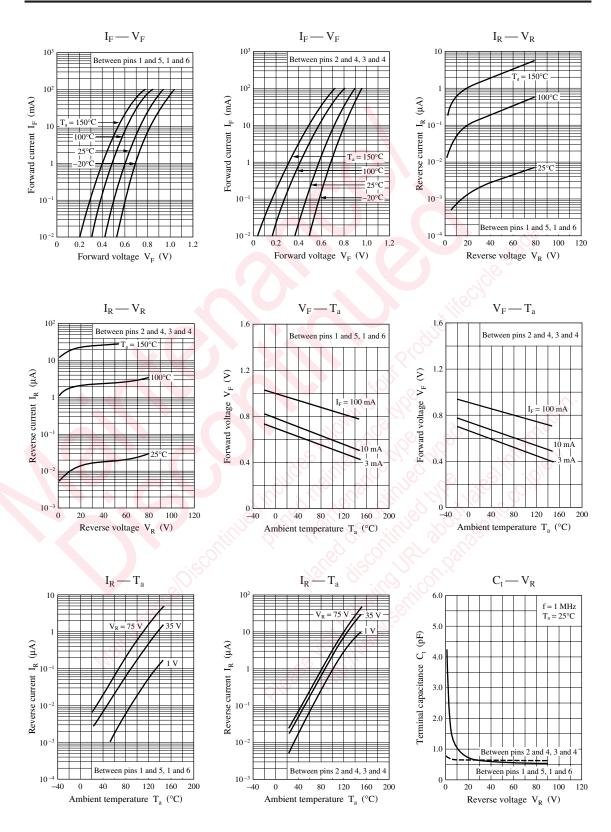
*3: t_{rr} measurement circuit



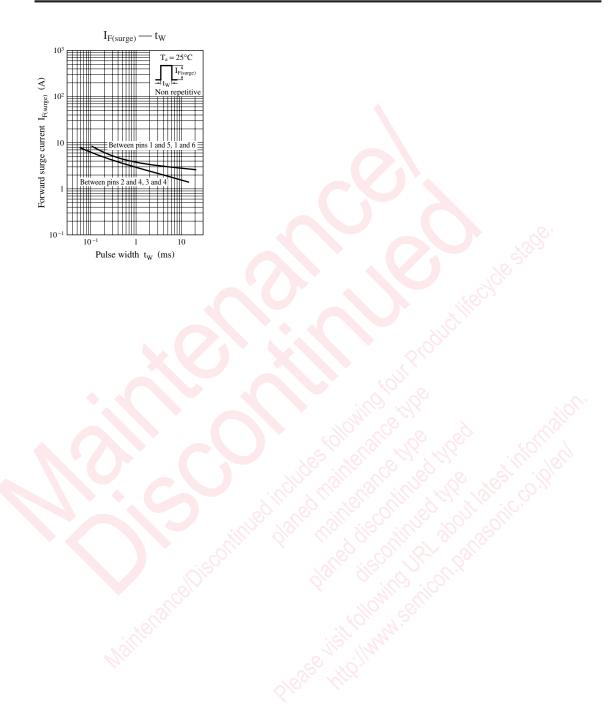
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